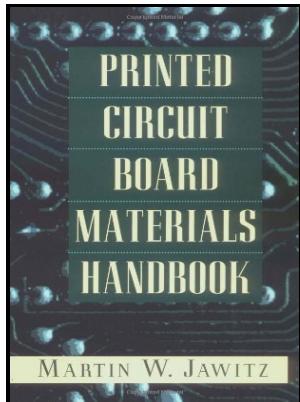


Electronic packaging and interconnection handbook

McGraw-Hill - Electronic Packaging and Interconnection Ser.: Electronic Materials and Processes Handbook by Charles A. Harper (1994, Hardcover) for sale online



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- Arab countries -- Politics and government.
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- Electronic packaging and interconnection handbook
- Electronic packaging and interconnection handbook
- Notes: Includes bibliographical references and index.
- This edition was published in 1991



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THE MOST COMPREHENSIVE REFERENCE IN ELECTRONIC PACKAGING—COMPLETELY UPDATED From new materials and technologies to increasingly prevalent lead-free manufacturing practices, Electronic Packaging and Interconnection Handbook offers a unique source of key reference data, practical guidance, and circuit and package design basics. Written by a team of experts from around the globe, this remarkable volume covers all aspects of electronic packaging, including: Materials Thermal Management Shock, Vibration, and Operational Stress Management Connector and Interconnection Technologies Soldering and Cleaning Technologies Single Chip Packaging and Ball Grid Arrays Surface Mount Technology Hybrid and Multichip Modules Chip-Scale, Flip-Chip, and Direct-Chip Attachment Rigid and Flexible Printed-Wiring Boards Packaging High-Speed and Microwave Systems Packaging High-Voltage Systems Packaging of MEMs Systems Packaging of Optoelectronic Systems CONTRIBUTORSPREFACE Chapter 1: Plastics, Elastomers, and Composites Chapter 2: Adhesives, Underfills, and Coatings Chapter 3: Thermal Management Chapter 4: Connector and Interconnection Technology Chapter 5: Solder Technologies for Electronic Packaging and Assembly Chapter 6: Packaging and Interconnection of Integrated Circuits Chapter 7: Hybrid Microelectronics and Multichip Modules Chapter 8: Chip Scale, Flip Chip, and Advanced Chip Packaging Technologies Chapter 9: Rigid and Flexible Printed Circuit Board Technology Chapter 10: Packaging of High-Speed and Microwave Electronic Systems INDEX Intended for electronic engineers, this handbook describes the various approaches to handling thermal management issues in electronic packaging, the function and structure of connectors, and the properties of solder technologies for electronic assembly.

This thoroughly revised and expanded Fourth Edition adds new information on key MEMs; optoelectronic, single-chip, and high-speed technologies; and updates important chapters on ball grid array and flip chip technologies. Thermal Management in Electronic Packaging, Chip Scale Packaging and Direct Chip Attach Technologies.

Electronic Packaging and Interconnection Handbook 4/E : Charles Harper : 9780071430487

Harper is a graduate of the Johns Hopkins University School of Engineering, where he also served as adjunct professor.

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